

## Snubberless™ high temperature 20 A Triacs

### Main features

Symbol	Value	Unit
$I_{T(RMS)}$	20	A
$V_{DRM}/V_{RRM}$	600	V
$I_{GT} (Q1)$	35	mA
$T_j \text{ MAX}$	150	°C

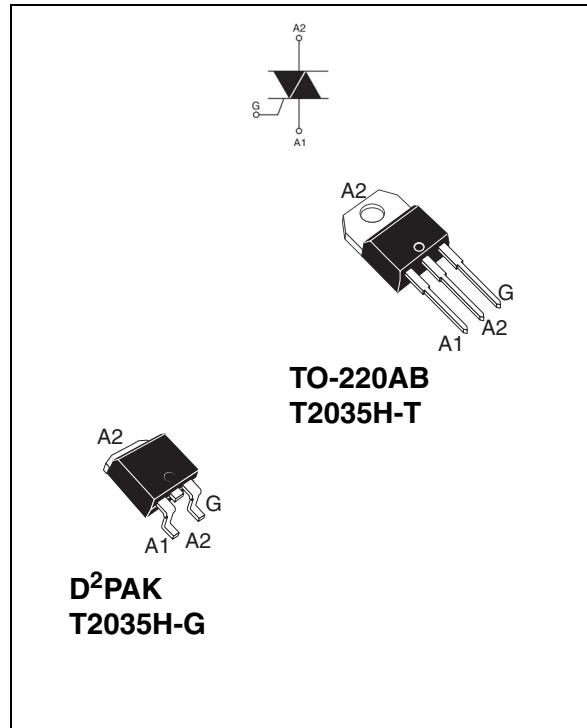
### Description

Specifically designed to operate at 150° C, the new 20 A T2035H Triacs provide an enhanced performance in terms of power loss and thermal dissipation. This facilitates the optimization of heatsink dimensioning, leading to improved space and cost effectiveness when compared to electro-mechanical solutions.

Based on ST Snubberless™ technology, the T2035H series offers high commutation switching capabilities and high noise immunity levels on the full range of  $T_j$ .

The T2035H series facilitates the optimization of the control of universal motors and inductive loads found in appliances such as vacuum cleaners, and washing machines.

The T2035H Triacs are also suitable for use in high temperature environment found in hot appliances such as cookers, ovens, hobs, electric heaters, and coffee machines.



### Order code

Part number	Marking
T2035H-600G	T2035H-600G
T2035H-600G-TR	T2035H-600G
T2035H-600TRG	T2035H-600T

TM: Snubberless is a trademark of STMicroelectronics

# 1 Characteristics

**Table 1. Absolute maximum ratings**

Symbol	Parameter			Value	Unit
$I_{T(RMS)}$	RMS on-state current (full sine wave)		$T_c = 127^\circ C$	20	A
$I_{TSM}$	Non repetitive surge peak on-state current (full cycle sine wave, $T_j$ initial = $25^\circ C$ )	$F = 60$ Hz	$t = 16.7$ ms	210	A
		$F = 50$ Hz	$t = 20$ ms	200	
$I^2t$	$I^2t$ Value for fusing		$t_p = 10$ ms	283	$A^2s$
$dI/dt$	Critical rate of rise of on-state current $I_G = 2xI_{GT}$ , $t_r \leq 100$ ns	$F = 120$ Hz	$T_j = 125^\circ C$	50	$A/\mu s$
$V_{DSM}/V_{RSM}$	Non repetitive surge peak off state voltage		$T_j = 25^\circ C$	700	V
$I_{GM}$	Peak gate current	$t_p = 20$ $\mu s$	$T_j = 150^\circ C$	4	A
$P_{G(AV)}$	Average gate power dissipation		$T_j = 150^\circ C$	1	W
$T_{stg}$ $T_j$	Storage junction temperature range Operating junction temperature range			-40 to +150 -30 to +150	$^\circ C$
$T_I$	Maximum leads soldering temperature during 10 s			260	$^\circ C$

**Table 2. Electrical characteristics ( $T_j = 25^\circ C$ , unless otherwise specified)**

Symbol	Test conditions	Quadrant		Value	Unit
$I_{GT}$ <sup>(1)</sup>	$V_D = 12$ V, $R_L = 33$ $\Omega$	I - II - III	MAX	35	mA
$V_{GT}$		I - II - III	MAX	1.3	V
$V_{GD}$	$V_D = V_{DRM}$ , $R_L = 3.3$ k $\Omega$ , $T_j = 150^\circ C$	I - II - III	MIN	0.15	V
$I_H$ <sup>(2)</sup>	$I_T = 100$ mA		MAX	35	mA
$I_L$	$I_G = 1.2 \times I_{GT}$	I - III	MAX	50	mA
		II		80	
$dV/dt$ <sup>(2)</sup>	$V_D = 67\% V_{DRM}$ , gate open, $T_j = 150^\circ C$		MIN	300	$V/\mu s$
$(dI/dt)c$ <sup>(2)</sup>	Without snubber, $T_j = 150^\circ C$		MIN	8.9	A/ms

1. minimum  $I_{GT}$  is guaranteed at 5% of  $I_{GT}$  max

2. for both polarities of A2 referenced to A1

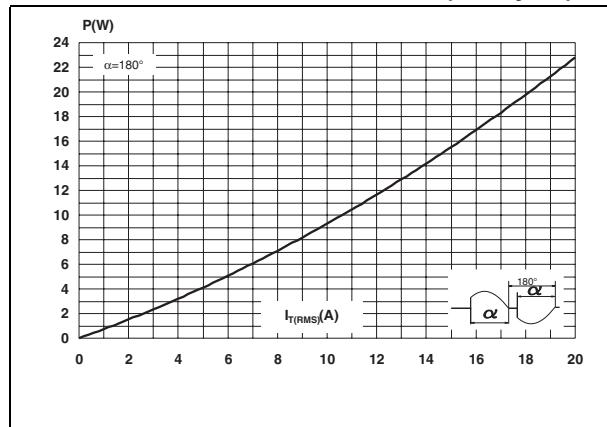
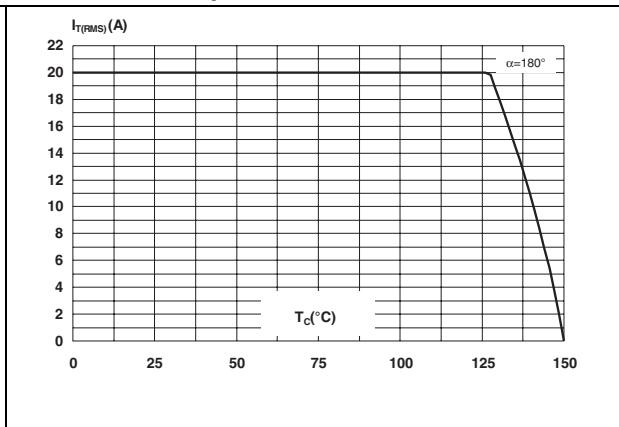
**Table 3. Static electrical characteristics**

Symbol	Test conditions			Value	Unit
$V_{TM}^{(1)}$	$I_{TM} = 28 \text{ A}$ , $t_p = 380 \mu\text{s}$	$T_j = 25^\circ \text{C}$	MAX	1.5	V
$V_{TO}^{(1)}$		$T_j = 150^\circ \text{C}$	MAX	0.80	V
$R_D^{(1)}$		$T_j = 150^\circ \text{C}$	MAX	21	$\text{m}\Omega$
$I_{DRM}$ $I_{RRM}$	$V_{DRM} = V_{RRM}$	$T_j = 25^\circ \text{C}$	MAX	5	$\mu\text{A}$
		$T_j = 150^\circ \text{C}$		7.4	mA
	$V_D/V_R = 400 \text{ V}$ (at peak mains voltage)	$T_j = 150^\circ \text{C}$		4.8	

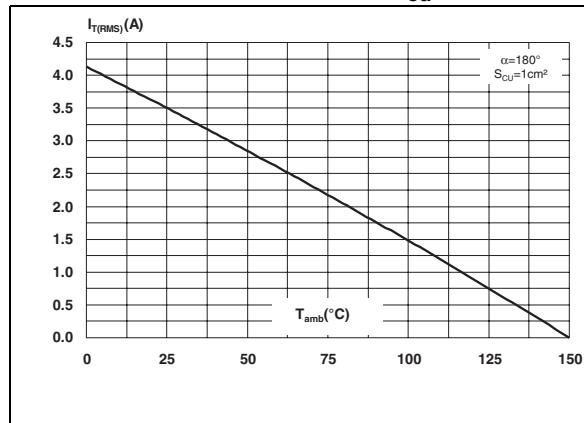
1. for both polarities of A2 referenced to A1

**Table 4. Thermal resistance**

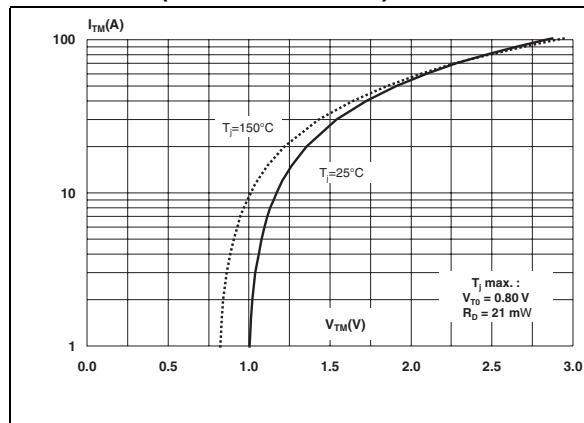
Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case for full (AC)	D <sup>2</sup> PAK TO-220AB	1	°C/W
$R_{th(j-a)}$	Junction to ambient	$S = 1 \text{ cm}^2$	D <sup>2</sup> PAK	
			TO-220AB	

**Figure 1. Maximum power dissipation vs RMS on-state current (full cycle)****Figure 2. RMS on-state current versus case temperature**

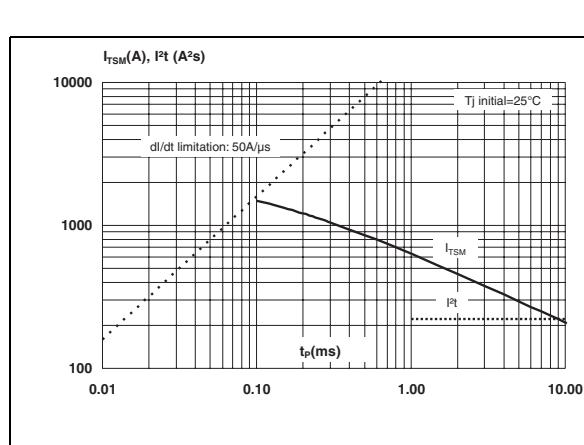
**Figure 3. RMS on-state current vs ambient temperature (epoxy printed circuit board FR4  $e_{cu} = 35 \mu m$ )**



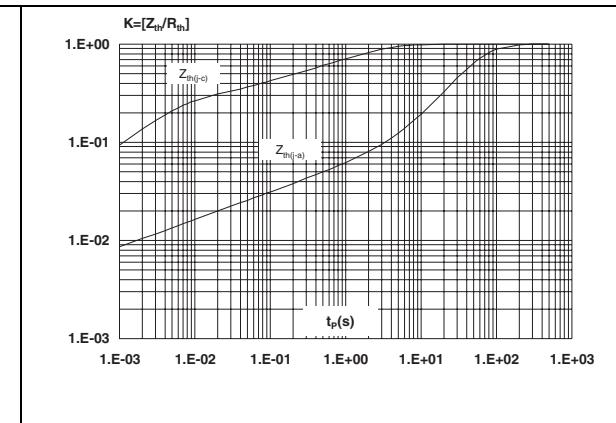
**Figure 5. On-state characteristics (maximum values)**



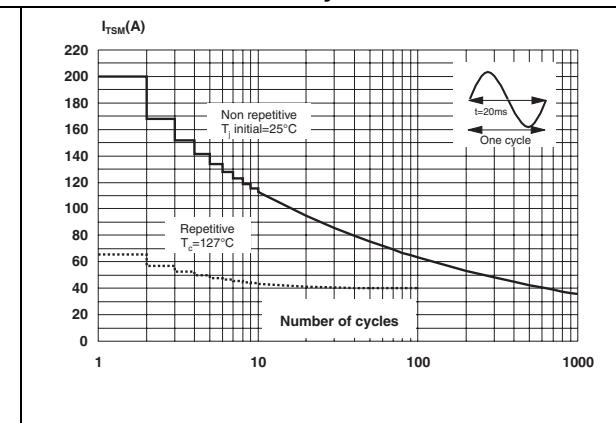
**Figure 7. Non repetitive surge peak on-state current (sinusoidal pulse width  $t_p < 10 \text{ ms}$ ) and value of  $I^2t$**



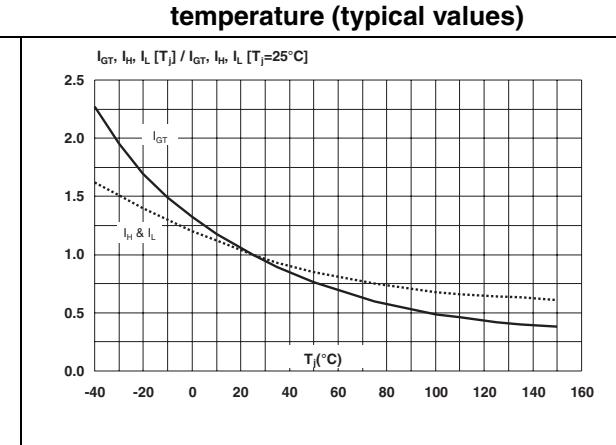
**Figure 4. Relative variation of thermal impedance vs pulse duration**



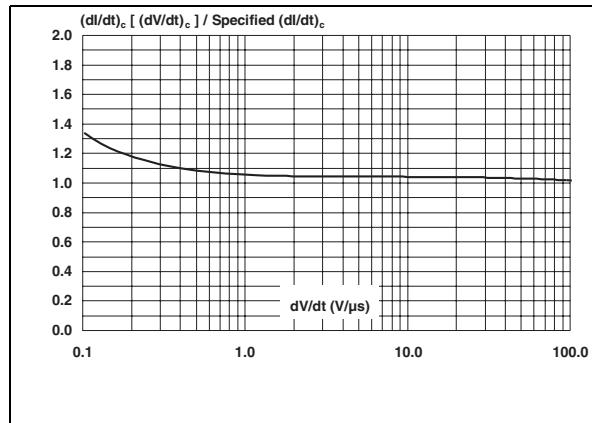
**Figure 6. Surge peak on-state current vs number of cycles**



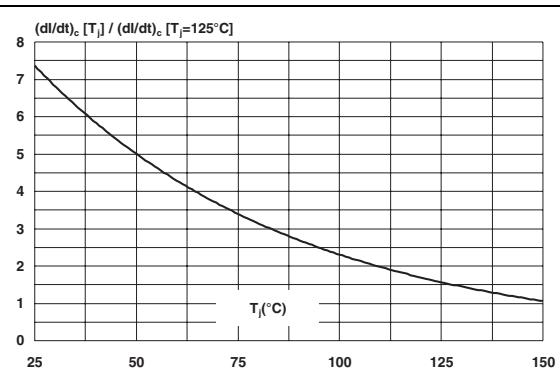
**Figure 8. Relative variation of gate trigger current, holding current and latching current vs junction temperature (typical values)**



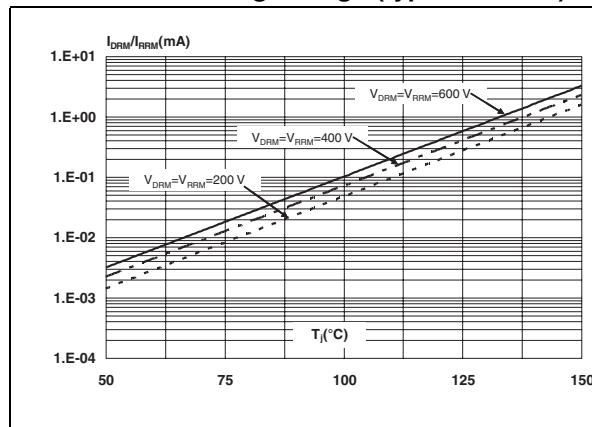
**Figure 9. Relative variation of critical rate of decrease of main current ( $di/dt$ ) vs reapplyed ( $dV/dt$ )**



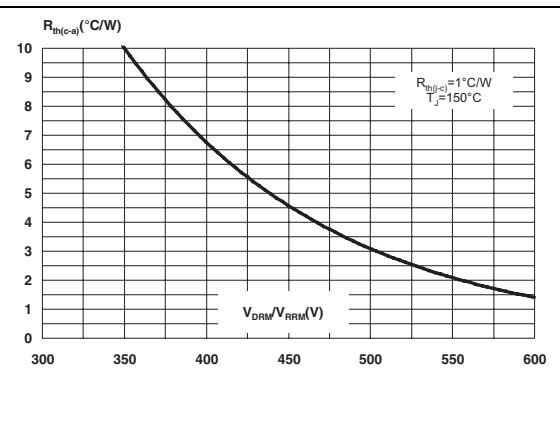
**Figure 10. Relative variation of critical rate of decrease of main current ( $di/dt$ )c versus junction temperature**



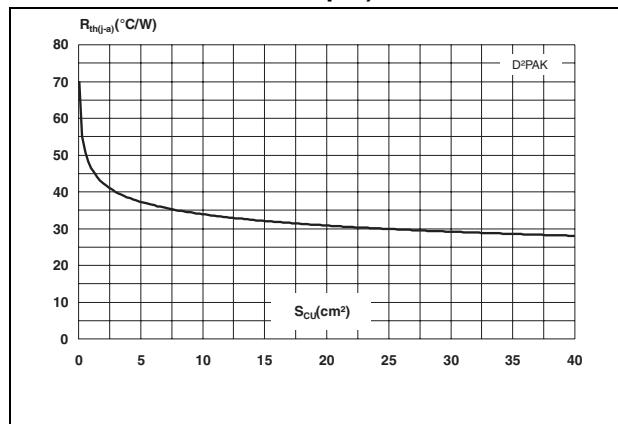
**Figure 11. Leakage current versus junction temperature for different values of blocking voltage (typical values)**



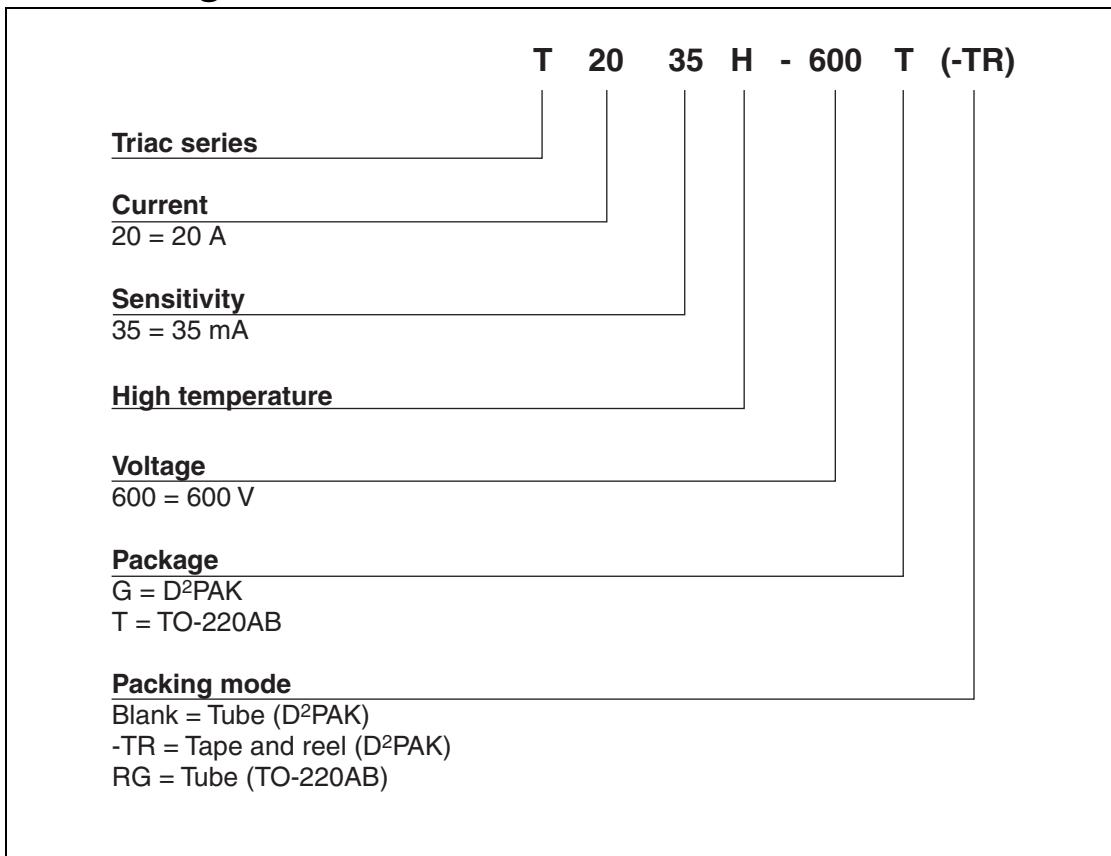
**Figure 12. Acceptable repetitive peak off-state voltage versus case-ambient thermal resistance**



**Figure 13. D<sup>2</sup>PAK junction to ambient thermal resistance versus copper surface under tab (PCB FR4, copper thickness 35 μm)**



## 2 Ordering information scheme



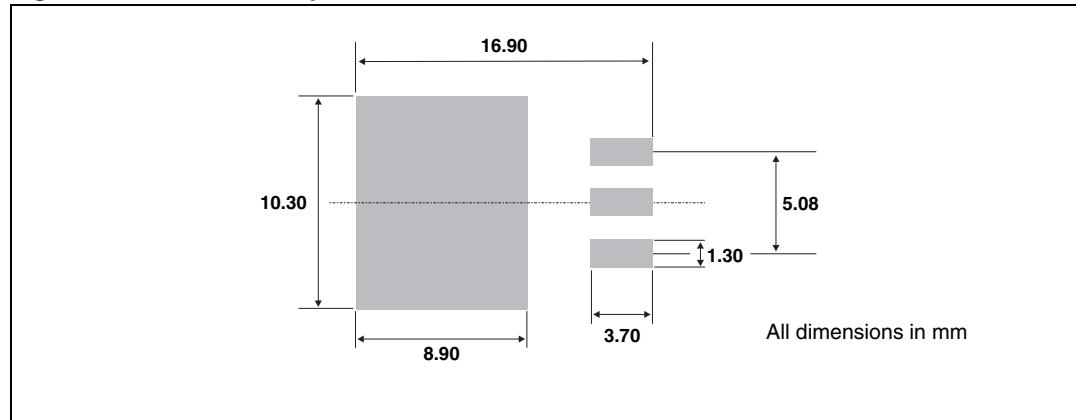
### 3 Package information

Table 5. TO-220AB dimensions

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.20		15.90	0.598		0.625
a1		3.75			0.147	
a2	13.00		14.00	0.511		0.551
B	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
C	4.40		4.60	0.173		0.181
c1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
e	2.40		2.70	0.094		0.106
F	6.20		6.60	0.244		0.259
ØI	3.75		3.85	0.147		0.151
I4	15.80	16.40	16.80	0.622	0.646	0.661
L	2.65		2.95	0.104		0.116
I2	1.14		1.70	0.044		0.066
I3	1.14		1.70	0.044		0.066
M		2.60			0.102	

Table 6. D<sup>2</sup>PAK dimensions

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

Figure 14. D<sup>2</sup>PAK Footprint

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com).

## 4 Ordering information

Part number	Marking	Package	Weight	Base Qty	Packing mode
T2035H-600G	T2035H-600G	D <sup>2</sup> PAK	1.5 g	50	Tube
T2035H-600G-TR	T2035H-600G	D <sup>2</sup> PAK	1.5 g	1000	Tape and Reel
T2035H-600TRG	T2035H-600T	TO-220AB	2.3 g	50	Tube

## 5 Revision history

Date	Revision	Changes
13-Jul-2006	1	Initial release.

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